

**ABSTRACT OF THE DISCLOSURE**

A Method for discharge prevention during interconnection. A first metal layer is formed on a substrate and a dielectric layer is then formed on the substrate, covering the first metal layer. Two via holes are formed in the dielectric layer, exposing one end of the first metal layer, wherein the first via hole is nearer the end of the first metal layer than the second via hole. The second via hole is then filled to form a conductive via plug to electrically connect the first meal layer. A second metal layer is formed on the dielectric layer to electrically connect the conductive via plug.